

1. Overview

This MCU is built using the high-performance silicon gate CMOS process using a R8C/Tiny Series CPU core and is packaged in a 32-pin plastic molded LQFP. This MCU operates using sophisticated instructions featuring a high level of instruction efficiency. With 1M bytes of address space, it is capable of executing instructions at high speed.

1.1 Applications

Electric household appliance, office equipment, housing equipment (sensor, security), general industrial equipment, audio, etc.

1.2 Performance Outline

Table 1.1. lists the performance outline of this MCU.

Table 1.1 Performance outline

Item		Performance
CPU	Number of basic instructions	89 instructions
	Shortest instruction execution time	50 ns ($f(X_{IN}) = 20$ MHz, $V_{CC} = 3.0$ to 5.5 V) 100 ns ($f(X_{IN}) = 10$ MHz, $V_{CC} = 2.7$ to 5.5 V)
	Operating mode	Single-chip
	Address space	1M bytes
	Memory capacity	See Table 1.2.
Peripheral function	Interrupt	Internal: 11 factors, External: 5 factors, Software: 4 factors, Priority level: 7 levels
	Watchdog timer	15 bits x 1 (with prescaler)
	Timer	Timer X: 8 bits x 1 channel, Timer Y: 8 bits x 1 channel, Timer Z: 8 bits x 1 channel (Each timer equipped with 8-bit prescaler) Timer C: 16 bits x 1 channel Circuits of input capture and output compare.
	Serial Interface	•1 channel Clock synchronous, UART •1 channel UART
	A/D converter	10-bit A/D converter: 1 circuit, 12 channels
	Clock generation circuit	2 circuits •Main clock generation circuit (Equipped with a built-in feedback resistor) •On-chip oscillator (high speed, low speed) On high-speed on-chip oscillator the frequency adjustment function is usable.
	Oscillation stop detection function	Stop detection of main clock oscillation
	Voltage detection circuit	Included
	Power on reset circuit	Included
	Port	Input/Output: 22 (including LED drive port), Input: 2 (LED drive I/O port: 8)
Electrical characteristics	Power supply voltage	$V_{CC} = 3.0$ to 5.5 V ($f(X_{IN}) = 20$ MHz) $V_{CC} = 2.7$ to 5.5 V ($f(X_{IN}) = 10$ MHz)
	Power consumption	Typ. 9 mA ($V_{CC} = 5.0$ V, ($f(X_{IN}) = 20$ MHz, High-speed mode) Typ. 5 mA ($V_{CC} = 3.0$ V, ($f(X_{IN}) = 10$ MHz, High-speed mode) Typ. 35 μ A ($V_{CC} = 3.0$ V, Wait mode, Peripheral clock stops) Typ. 0.7 μ A ($V_{CC} = 3.0$ V, Stop mode)
Flash memory	Program/erase voltage	$V_{CC} = 2.7$ to 5.5 V
	Number of program/erase	100 times
Operating ambient temperature		-20 to 85 °C -40 to 85 °C (D-version)
Package		32-pin plastic mold LQFP

1.3 Block Diagram

Figure 1.1 shows this MCU block diagram.

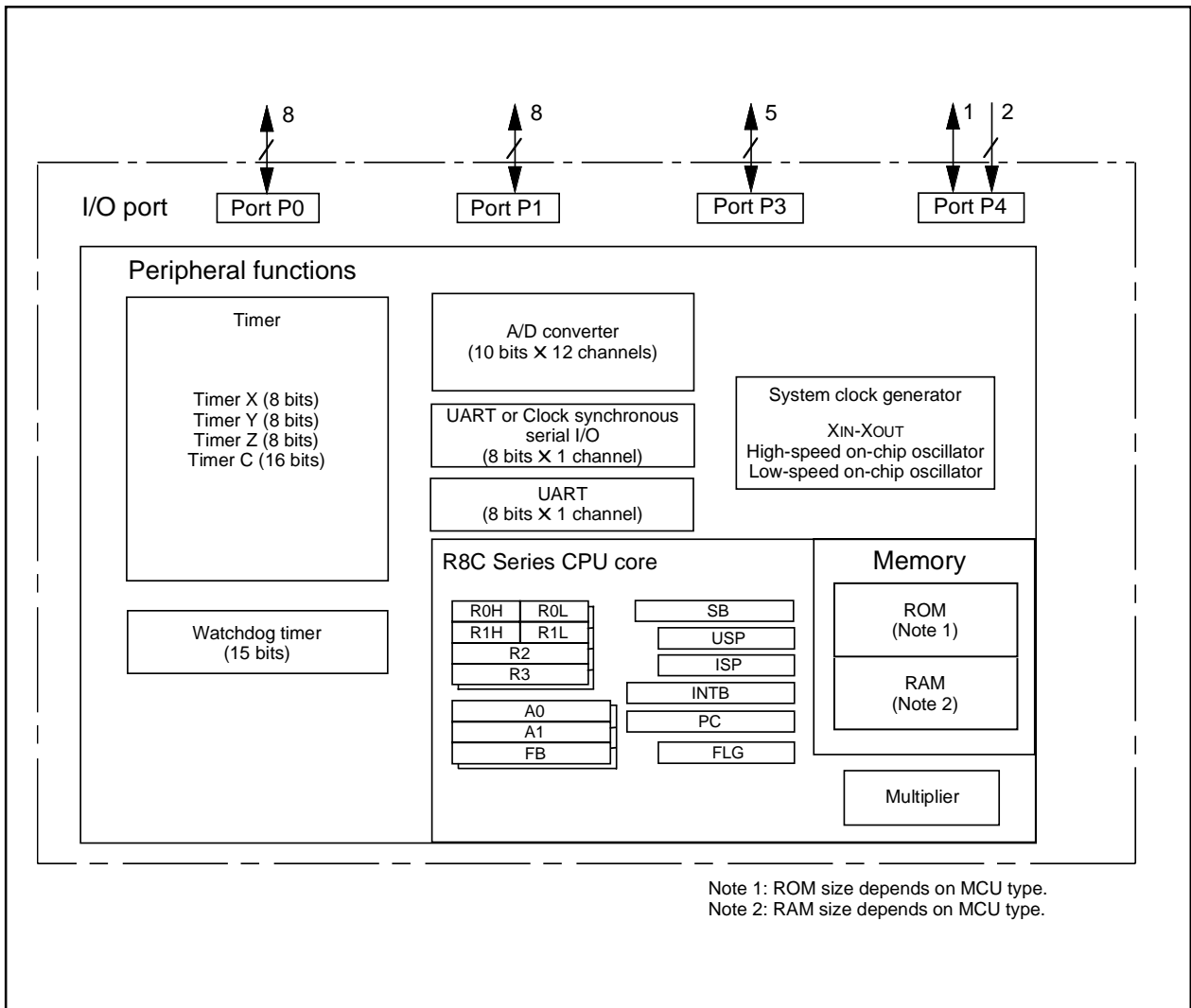


Figure 1.1 Block Diagram

1.4 Product List

Table 1.2 lists the products.

Table 1.2 Product List

As of Sep. 2004

Type No.	ROM capacity	RAM capacity	Package type	Remarks
R5F21112FP	8K bytes	512 bytes	32P6U-A	Flash memory version
R5F21113FP	12K bytes	768 bytes	32P6U-A	
R5F21114FP	16K bytes	1K bytes	32P6U-A	
R5F21112DFP	8K bytes	512 bytes	32P6U-A	D version
R5F21113DFP	12K bytes	768 bytes	32P6U-A	
R5F21114DFP	16K bytes	1K bytes	32P6U-A	

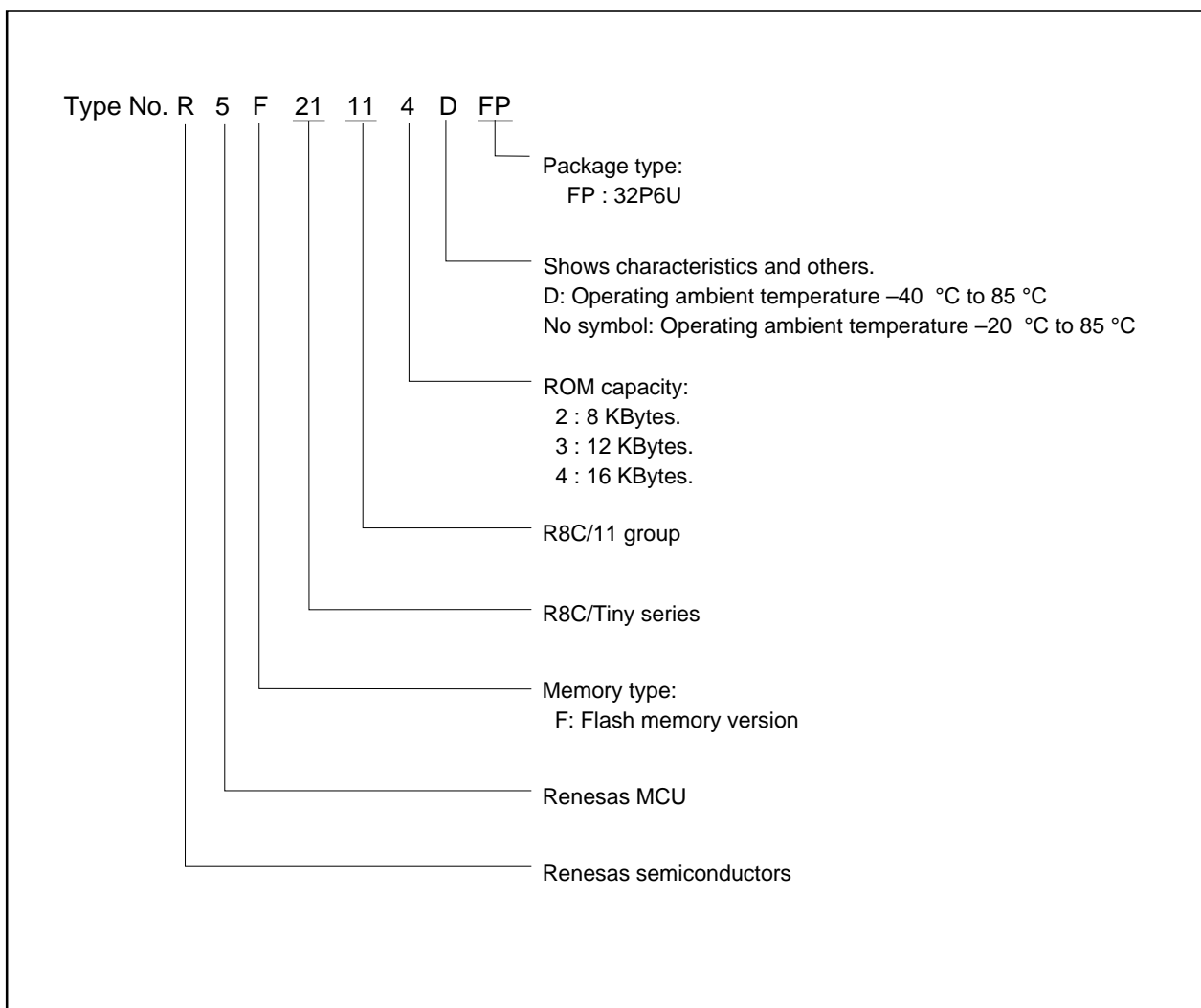


Figure 1.2 Type No., Memory Size, and Package

1.5 Pin Configuration

Figure 1.3 shows the pin configuration (top view).

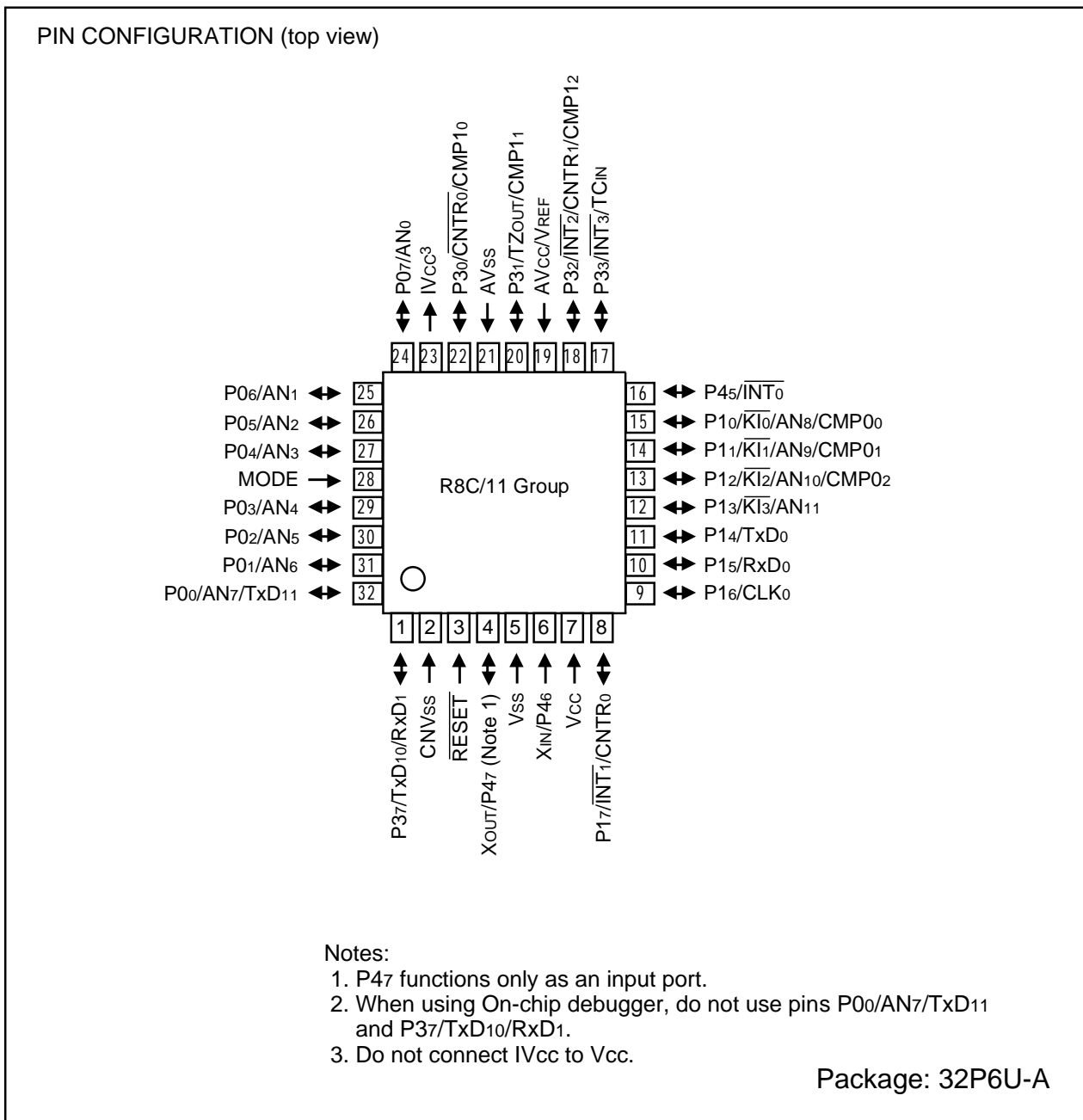


Figure 1.3 Pin Configuration (Top View)

1.6 Pin Description

Table 1.3 shows the pin description

Table 1.3 Pin description

Signal name	Pin name	I/O type	Function
Power supply input	Vcc, Vss	I	Apply 2.7 V to 5.5 V to the Vcc pin. Apply 0 V to the Vss pin.
IVcc	IVcc	O	This pin is to stabilize internal power supply. Connect this pin to Vss via a capacitor (0.1 μ F). Do not connect to Vcc.
Analog power supply input	AVcc, AVss	I	These are power supply input pins for A/D converter. Connect the AVss pin to Vss. Connect a capacitor between pins AVcc and AVss.
Reset input	RESET	I	"L" on this input resets the MCU.
CNVss	CNVss	I	Connect this pin to Vss via a resistor.
MODE	MODE	I	Connect this pin to Vcc via a resistor.
Main clock input	XIN	I	These pins are provided for the main clock generating circuit I/O. Connect a ceramic resonator or a crystal oscillator between the XIN and XOUT pins. To use an externally derived clock, input it to the XIN pin and leave the XOUT pin open.
Main clock output	XOUT	O	
INT interrupt input	INT $\bar{0}$ to INT $\bar{3}$	I	These are INT interrupt input pins.
Key input interrupt	KI $\bar{0}$ to KI $\bar{3}$	I	These are key input interrupt pins.
Timer X	CNTR $\bar{0}$	I/O	This is the timer X I/O pin.
	CNTR $\bar{0}$	O	This is the timer X output pin.
Timer Y	CNTR $\bar{1}$	I/O	This is the timer Y I/O pin.
Timer Z	TZOUT	O	This is the timer Z output pin.
Timer C	TCIN	I	This is the timer C input pin.
	CMP $\bar{0}$ to CMP $\bar{3}$, CMP $\bar{10}$ to CMP $\bar{13}$	O	These are the timer C output pins.
Serial interface	CLK $\bar{0}$	I/O	This is a transfer clock I/O pin.
	RxD $\bar{0}$, RxD $\bar{1}$	I	These are serial data input pins.
	TxD $\bar{0}$, TxD $\bar{10}$, TxD $\bar{11}$	O	These are serial data output pins.
Reference voltage input	VREF	I	This is a reference voltage input pin for A/D converter.
A/D converter	AN $\bar{0}$ to AN $\bar{11}$	I	These are analog input pins for A/D converter.
I/O port	P $\bar{0}$ to P $\bar{7}$, P $\bar{10}$ to P $\bar{17}$, P $\bar{30}$ to P $\bar{33}$, P $\bar{37}$, P $\bar{45}$	I/O	These are 8-bit CMOS I/O ports. Each port has an input/output select direction register, allowing each pin in that port to be directed for input or output individually. Any port set to input can select whether to use a pull-up resistor or not by program. P $\bar{10}$ to P $\bar{17}$ also function as LED drive ports.
Input port	P $\bar{46}$, P $\bar{47}$	I	These are input only pins.

2. Central Processing Unit (CPU)

Figure 2.1 shows the CPU registers. The CPU has 13 registers. Of these, R0, R1, R2, R3, A0, A1 and FB comprise a register bank. There are two register banks.

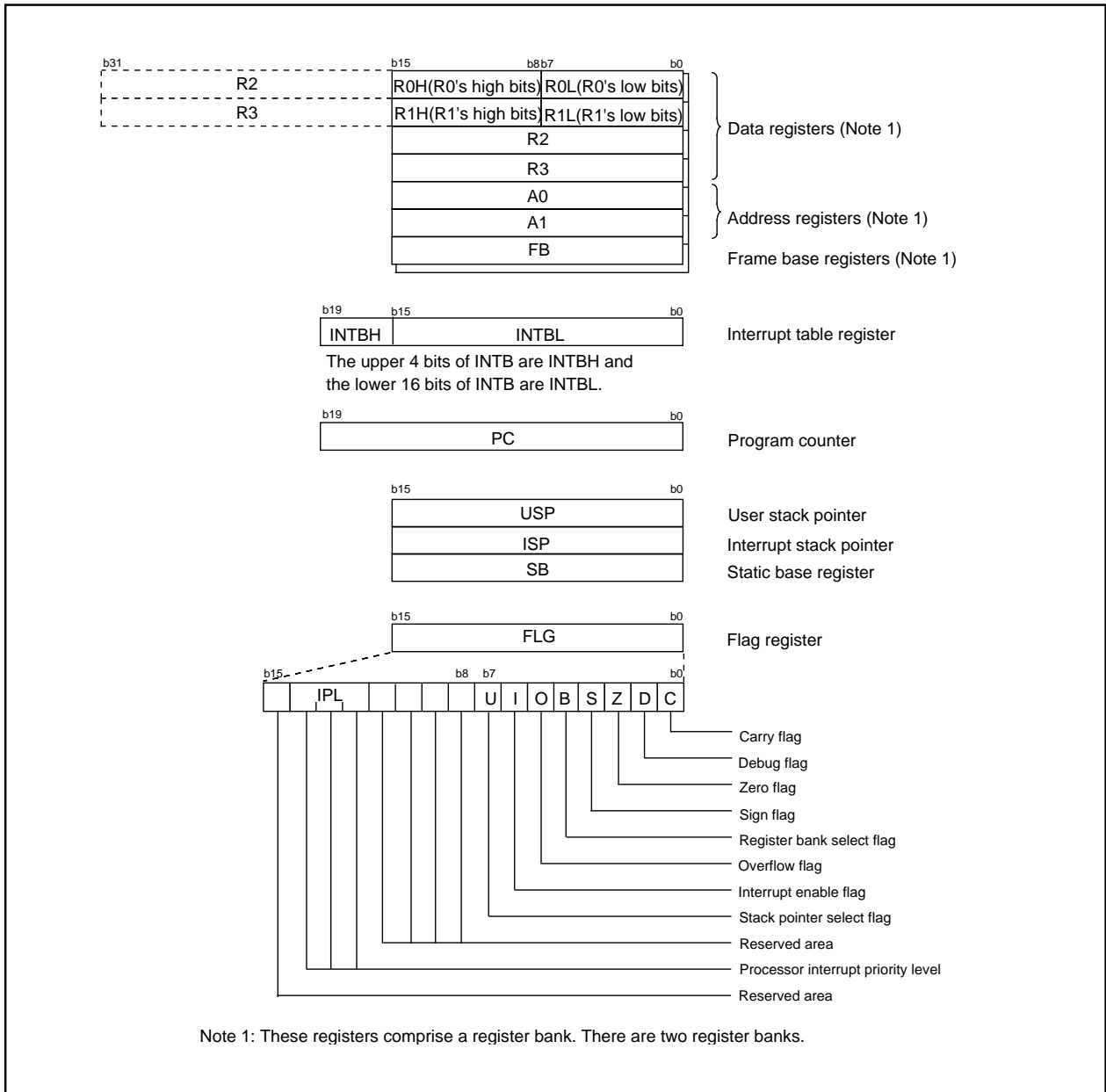


Figure 2.1. Central Processing Unit Register

2.1 Data Registers (R0, R1, R2 and R3)

The R0 register consists of 16 bits, and is used mainly for transfers and arithmetic/logic operations. R1 to R3 are the same as R0.

The R0 register can be separated between high (R0H) and low (R0L) for use as two 8-bit data registers. R1H and R1L are the same as R0H and R0L. Conversely, R2 and R0 can be combined for use as a 32-bit data register (R2R0). R3R1 is the same as R2R0.

2.2 Address Registers (A0 and A1)

The register A0 consists of 16 bits, and is used for address register indirect addressing and address register relative addressing. They also are used for transfers and logic/logic operations. A1 is the same as A0.

In some instructions, registers A1 and A0 can be combined for use as a 32-bit address register (A1A0).

2.3 Frame Base Register (FB)

FB is configured with 16 bits, and is used for FB relative addressing.

2.4 Interrupt Table Register (INTB)

INTB is configured with 20 bits, indicating the start address of an interrupt vector table.

2.5 Program Counter (PC)

PC is configured with 20 bits, indicating the address of an instruction to be executed.

2.6 User Stack Pointer (USP) and Interrupt Stack Pointer (ISP)

Stack pointer (SP) comes in two types: USP and ISP, each configured with 16 bits.

Your desired type of stack pointer (USP or ISP) can be selected by the U flag of FLG.

2.7 Static Base Register (SB)

SB is configured with 16 bits, and is used for SB relative addressing.

2.8 Flag Register (FLG)

FLG consists of 11 bits, indicating the CPU status.

2.8.1 Carry Flag (C Flag)

This flag retains a carry, borrow, or shift-out bit that has occurred in the arithmetic/logic unit.

2.8.2 Debug Flag (D Flag)

The D flag is used exclusively for debugging purpose. During normal use, it must be set to "0".

2.8.3 Zero Flag (Z Flag)

This flag is set to "1" when an arithmetic operation resulted in 0; otherwise, it is "0".

2.8.4 Sign Flag (S Flag)

This flag is set to "1" when an arithmetic operation resulted in a negative value; otherwise, it is "0".

2.8.5 Register Bank Select Flag (B Flag)

Register bank 0 is selected when this flag is "0"; register bank 1 is selected when this flag is "1".

2.8.6 Overflow Flag (O Flag)

This flag is set to "1" when the operation resulted in an overflow; otherwise, it is "0".

2.8.7 Interrupt Enable Flag (I Flag)

This flag enables a maskable interrupt.

Maskable interrupts are disabled when the I flag is "0", and are enabled when the I flag is "1". The I flag is cleared to "0" when the interrupt request is accepted.

2.8.8 Stack Pointer Select Flag (U Flag)

ISP is selected when the U flag is "0"; USP is selected when the U flag is "1".

The U flag is cleared to "0" when a hardware interrupt request is accepted or an INT instruction for software interrupt Nos. 0 to 31 is executed.

2.8.9 Processor Interrupt Priority Level (IPL)

IPL is configured with three bits, for specification of up to eight processor interrupt priority levels from level 0 to level 7.

If a requested interrupt has priority greater than IPL, the interrupt is enabled.

2.8.10 Reserved Area

When write to this bit, write "0". When read, its content is indeterminate.

3. Memory

Figure 3.1 is a memory map of this MCU. The address space extends the 1M bytes from address 00000₁₆ to FFFFF₁₆.

The internal ROM is allocated in a lower address direction beginning with address 0FFFF₁₆. For example, a 16-Kbyte internal ROM is allocated to the addresses from 0C000₁₆ to 0FFFF₁₆.

The fixed interrupt vector table is allocated to the addresses from 0FFDC₁₆ to 0FFFF₁₆. Therefore, store the start address of each interrupt routine here.

The internal RAM is allocated in an upper address direction beginning with address 00400₁₆. For example, a 1-Kbyte internal RAM is allocated to the addresses from 00400₁₆ to 007FF₁₆. In addition to storing data, the internal RAM also stores the stack used when calling subroutines and when interrupts are generated. Special function registers (SFR) are allocated to the addresses from 00000₁₆ to 002FF₁₆. Peripheral function control registers are located here. Of the SFR, any space which has no functions allocated is reserved for future use and cannot be used by users.

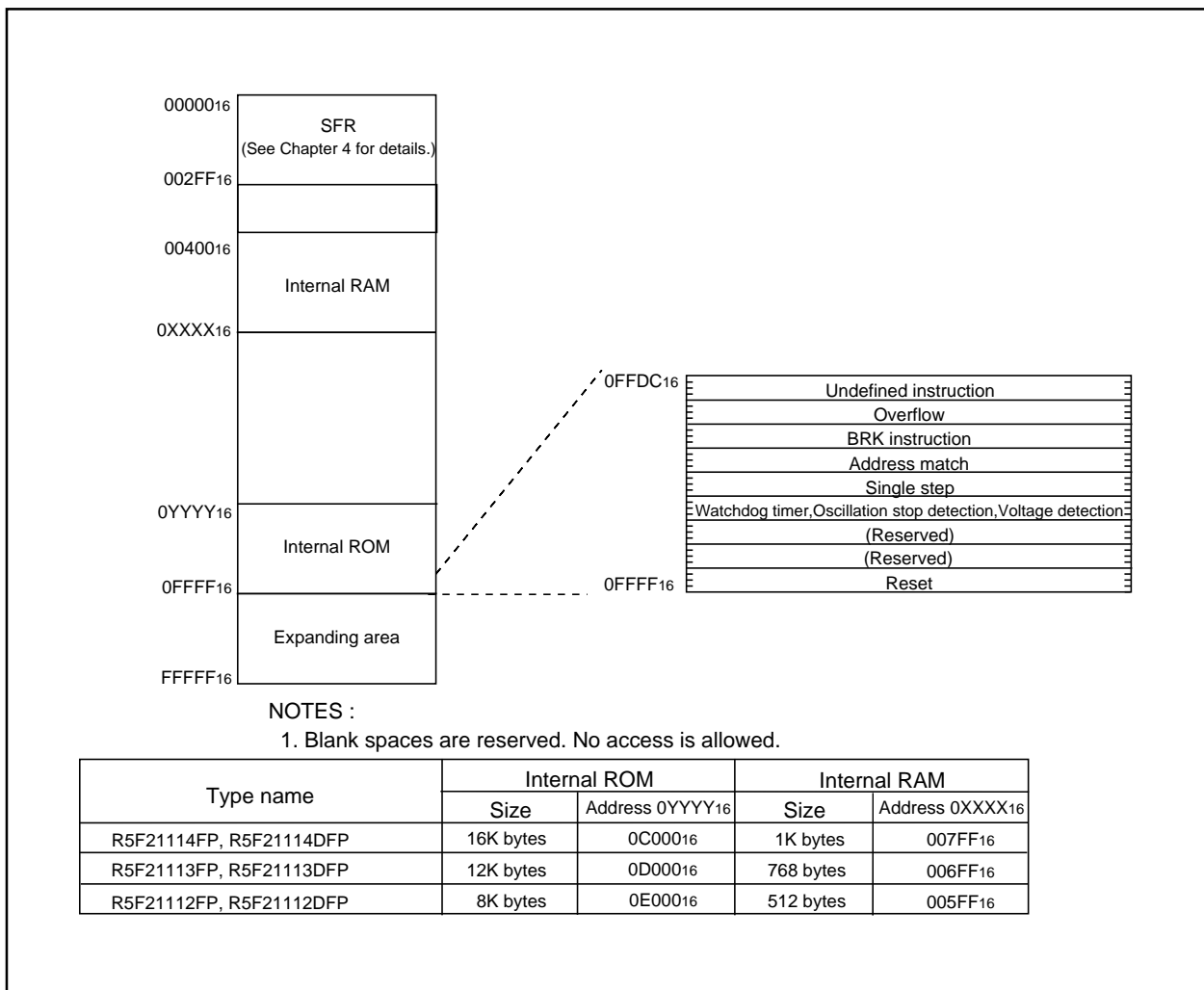


Figure 3.1 Memory Map

4. Special Function Register (SFR)

SFR(Special Function Register) is the control register of peripheral functions. Tables 4.1 to 4.4 list the SFR information

Table 4.1 SFR Information(1)(1)

Address	Register	Symbol	After reset
0000 ₁₆			
0001 ₁₆			
0002 ₁₆			
0003 ₁₆			
0004 ₁₆	Processor mode register 0 ¹	PM0	00 ₁₆
0005 ₁₆	Processor mode register 1	PM1	00 ₁₆
0006 ₁₆	System clock control register 0	CM0	011010002
0007 ₁₆	System clock control register 1	CM1	001000002
0008 ₁₆	High-speed on-chip control register 0	HR0	00 ₁₆
0009 ₁₆	Address match interrupt enable register	AIER	XXXXXX002
000A ₁₆	Protect register	PRCR	00XXX0002
000B ₁₆	High-speed on-chip control register 1	HR1	40 ₁₆
000C ₁₆	Oscillation stop detection register	OCD	000001002
000D ₁₆	Watchdog timer reset register	WDTR	XX ₁₆
000E ₁₆	Watchdog timer start register	WDTS	XX ₁₆
000F ₁₆	Watchdog timer control register	WDC	000XXXXX2
0010 ₁₆	Address match interrupt register 0	RMAD0	00 ₁₆
0011 ₁₆			00 ₁₆
0012 ₁₆			X0 ₁₆
0013 ₁₆			
0014 ₁₆	Address match interrupt register 1	RMAD1	00 ₁₆
0015 ₁₆			00 ₁₆
0016 ₁₆			X0 ₁₆
0017 ₁₆			
0018 ₁₆			
0019 ₁₆	Voltage detection register 1 ²	VCR1	00 ₁₆
001A ₁₆	Voltage detection register 2 ²	VCR2	XXX00000 ₁₆
001B ₁₆			
001C ₁₆			
001D ₁₆			
001E ₁₆	INT0 input filter select register	INT0F	XXXXX0002
001F ₁₆	Voltage detection interrupt register ²	D4INT	0016 ³
0020 ₁₆			
0021 ₁₆			
0022 ₁₆			
0023 ₁₆			
0024 ₁₆			
0025 ₁₆			
0026 ₁₆			
0027 ₁₆			
0028 ₁₆			
0029 ₁₆			
002A ₁₆			
002B ₁₆			
002C ₁₆			
002D ₁₆			
002E ₁₆			
002F ₁₆			
0030 ₁₆			
0031 ₁₆			
0032 ₁₆			
0033 ₁₆			
0034 ₁₆			
0035 ₁₆			
0036 ₁₆			
0037 ₁₆			
0038 ₁₆			
0039 ₁₆			
003A ₁₆			
003B ₁₆			
003C ₁₆			
003D ₁₆			
003E ₁₆			
003F ₁₆			

010000012 ⁴

X : Undefined

NOTES:

- Blank columns are all reserved space. No access is allowed.
- Software reset or the watchdog timer reset does not affect this register.
- Owing to Reset input.
- In the case of RESET pin = H retaining.

Table 4.2 SFR Information(2)⁽¹⁾

Address	Register	Symbol	After reset
0040 ₁₆			
0041 ₁₆			
0042 ₁₆			
0043 ₁₆			
0044 ₁₆			
0045 ₁₆			
0046 ₁₆			
0047 ₁₆			
0048 ₁₆			
0049 ₁₆			
004A ₁₆			
004B ₁₆			
004C ₁₆			
004D ₁₆	Key input interrupt control register	KUPIC	XXXXX0002
004E ₁₆	A/D conversion interrupt control register	ADIC	XXXXX0002
004F ₁₆			
0050 ₁₆	Compare 1 interrupt control register	CMP1IC	XXXXX0002
0051 ₁₆	UART0 transmit interrupt control register	S0TIC	XXXXX0002
0052 ₁₆	UART0 receive interrupt control register	S0RIC	XXXXX0002
0053 ₁₆	UART1 transmit interrupt control register	S1TIC	XXXXX0002
0054 ₁₆	UART1 receive interrupt control register	S1RIC	XXXXX0002
0055 ₁₆	INT2 interrupt control register	INT2IC	XXXXX0002
0056 ₁₆	Timer X interrupt control register	TXIC	XXXXX0002
0057 ₁₆	Timer Y interrupt control register	TYIC	XXXXX0002
0058 ₁₆	Timer Z interrupt control register	TZIC	XXXXX0002
0059 ₁₆	INT1 interrupt control register	INT1IC	XXXXX0002
005A ₁₆	INT3 interrupt control register	INT3IC	XXXXX0002
005B ₁₆	Timer C interrupt control register	TCIC	XXXXX0002
005C ₁₆	Compare 0 interrupt control register	CMP0IC	XXXXX0002
005D ₁₆	INT0 interrupt control register	INT0IC	XX00X0002
005E ₁₆			
005F ₁₆			
0060 ₁₆			
0061 ₁₆			
0062 ₁₆			
0063 ₁₆			
0064 ₁₆			
0065 ₁₆			
0066 ₁₆			
0067 ₁₆			
0068 ₁₆			
0069 ₁₆			
006A ₁₆			
006B ₁₆			
006C ₁₆			
006D ₁₆			
006E ₁₆			
006F ₁₆			
0070 ₁₆			
0071 ₁₆			
0072 ₁₆			
0073 ₁₆			
0074 ₁₆			
0075 ₁₆			
0076 ₁₆			
0077 ₁₆			
0078 ₁₆			
0079 ₁₆			
007A ₁₆			
007B ₁₆			
007C ₁₆			
007D ₁₆			
007E ₁₆			
007F ₁₆			

X : Undefined

NOTES :

1. Blank columns are all reserved space. No access is allowed.

Table 4.3 SFR Information(3)⁽¹⁾

Address	Register	Symbol	After reset
0080 ₁₆	Timer Y, Z mode register	TYZMR	00 ₁₆
0081 ₁₆	Prescaler Y	PREY	FF ₁₆
0082 ₁₆	Timer Y secondary	TYSC	FF ₁₆
0083 ₁₆	Timer Y primary	TYPR	FF ₁₆
0084 ₁₆	Timer Y, Z waveform output control register	PUM	00 ₁₆
0085 ₁₆	Prescaler Z	PREZ	FF ₁₆
0086 ₁₆	Timer Z secondary	TZSC	FF ₁₆
0087 ₁₆	Timer Z primary	TZPR	FF ₁₆
0088 ₁₆			
0089 ₁₆			
008A ₁₆	Timer Y, Z output control register	TYZOC	00 ₁₆
008B ₁₆	Timer X mode register	TXMR	00 ₁₆
008C ₁₆	Prescaler X	PREX	FF ₁₆
008D ₁₆	Timer X register	TX	FF ₁₆
008E ₁₆	Timer count source setting register	TCSS	00 ₁₆
008F ₁₆			
0090 ₁₆	Timer C register	TC	00 ₁₆
0091 ₁₆			00 ₁₆
0092 ₁₆			
0093 ₁₆			
0094 ₁₆			
0095 ₁₆			
0096 ₁₆	External input enable register	INTEN	00 ₁₆
0097 ₁₆			
0098 ₁₆	Key input enable register	KIEN	00 ₁₆
0099 ₁₆			
009A ₁₆	Timer C control register 0	TCC0	00 ₁₆
009B ₁₆	Timer C control register 1	TCC1	00 ₁₆
009C ₁₆	Capture, compare 0 register	TM0	FF ₁₆
009D ₁₆			FF ₁₆
009E ₁₆	Compare 1 register	TM1	FF ₁₆
009F ₁₆			FF ₁₆
00A0 ₁₆	UART0 transmit/receive mode register	U0MR	00 ₁₆
00A1 ₁₆	UART0 bit rate register	U0BRG	XX ₁₆
00A2 ₁₆	UART0 transmit buffer register	U0TB	XX ₁₆
00A3 ₁₆			XX ₁₆
00A4 ₁₆	UART0 transmit/receive control register 0	U0C0	00001000 ₂
00A5 ₁₆	UART0 transmit/receive control register 1	U0C1	00000010 ₂
00A6 ₁₆	UART0 receive buffer register	U0RB	XX ₁₆
00A7 ₁₆			XX ₁₆
00A8 ₁₆	UART1 transmit/receive mode register	U1MR	00 ₁₆
00A9 ₁₆	UART1 bit rate register	U1BRG	XX ₁₆
00AA ₁₆	UART1 transmit buffer register	U1TB	XX ₁₆
00AB ₁₆			XX ₁₆
00AC ₁₆	UART1 transmit/receive control register 0	U1C0	00001000 ₂
00AD ₁₆	UART1 transmit/receive control register 1	U1C1	00000010 ₂
00AE ₁₆	UART1 receive buffer register	U1RB	XX ₁₆
00AF ₁₆			XX ₁₆
00B0 ₁₆	UART transmit/receive control register 2	UCON	00 ₁₆
00B1 ₁₆			
00B2 ₁₆			
00B3 ₁₆			
00B4 ₁₆			
00B5 ₁₆			
00B6 ₁₆			
00B7 ₁₆			
00B8 ₁₆			
00B9 ₁₆			
00BA ₁₆			
00BB ₁₆			
00BC ₁₆			
00BD ₁₆			
00BE ₁₆			
00BF ₁₆			

X : Undefined

NOTES :

1. Blank columns are all reserved space. No access is allowed.

Table 4.4 SFR Information(4)⁽¹⁾

Address	Register	Symbol	After reset
00C0 ₁₆	A/D register	AD	XX ₁₆
00C1 ₁₆			XX ₁₆
00C2 ₁₆			
00C3 ₁₆			
00C4 ₁₆			
00C5 ₁₆			
00C6 ₁₆			
00C7 ₁₆			
00C8 ₁₆			
00C9 ₁₆			
00CA ₁₆			
00CB ₁₆			
00CC ₁₆			
00CD ₁₆			
00CE ₁₆			
00CF ₁₆			
00D0 ₁₆			
00D1 ₁₆			
00D2 ₁₆			
00D3 ₁₆			
00D4 ₁₆	A/D control register 2	ADCON2	00 ₁₆
00D5 ₁₆			
00D6 ₁₆	A/D control register 0	ADCON0	00000XX ₂
00D7 ₁₆	A/D control register 1	ADCON1	00 ₁₆
00D8 ₁₆			
00D9 ₁₆			
00DA ₁₆			
00DB ₁₆			
00DC ₁₆			
00DD ₁₆			
00DE ₁₆			
00DF ₁₆			
00E0 ₁₆	Port P0 register	P0	XX ₁₆
00E1 ₁₆	Port P1 register	P1	XX ₁₆
00E2 ₁₆	Port P0 direction register	PD0	00 ₁₆
00E3 ₁₆	Port P1 direction register	PD1	00 ₁₆
00E4 ₁₆			
00E5 ₁₆	Port P3 register	P3	XX ₁₆
00E6 ₁₆			
00E7 ₁₆	Port P3 direction register	PD3	00 ₁₆
00E8 ₁₆	Port P4 register	P4	XX ₁₆
00E9 ₁₆			
00EA ₁₆	Port P4 direction register	PD4	00 ₁₆
00EB ₁₆			
00EC ₁₆			
00ED ₁₆			
00EE ₁₆			
00EF ₁₆			
00F0 ₁₆			
00F1 ₁₆			
00F2 ₁₆			
00F3 ₁₆			
00F4 ₁₆			
00F5 ₁₆			
00F6 ₁₆			
00F7 ₁₆			
00F8 ₁₆			
00F9 ₁₆			
03FA ₁₆			
00FB ₁₆			
00FC ₁₆	Pull-up control register 0	PUR0	00XX0000 ₂
00FD ₁₆	Pull-up control register 1	PUR1	XXXXXX0X ₂
00FE ₁₆	Port P1 drive capacity control register	DRR	00 ₁₆
00FF ₁₆	Timer C output control register	TCOUT	00 ₁₆
01B3 ₁₆	Flash memory control register 4	FMR4	01000000 ₂
01B4 ₁₆			
01B5 ₁₆	Flash memory control register 1	FMR1	0100XX0X ₂
01B6 ₁₆			
01B7 ₁₆	Flash memory control register 0	FMR0	00000012

X : Undefined

NOTES :

1. The blank areas, 0100₁₆ to 01B2₁₆ and 01B8₁₆ to 02FF₁₆ are reserved and cannot be used by users.

5. Electrical Characteristics

Table 5.1 Absolute Maximum Ratings

Symbol	Parameter	Condition	Rated value	Unit
V _{CC}	Supply voltage	V _{CC} =AV _{CC}	-0.3 to 6.5	V
AV _{CC}	Analog supply voltage	V _{CC} =AV _{CC}	-0.3 to 6.5	V
V _I	Input voltage		-0.3 to V _{CC} +0.3	V
V _O	Output voltage		-0.3 to V _{CC} +0.3	V
P _d	Power dissipation	T _{opr} =25 °C	300	mW
T _{opr}	Operating ambient temperature		-20 to 85 / -40 to 85 (D version)	°C
T _{stg}	Storage temperature		-65 to 150	°C

Table 5.2 Recommended Operating Conditions

Symbol	Parameter	Conditions	Standard			Unit	
			Min.	Typ.	Max.		
V _{CC}	Supply voltage		2.7	—	5.5	V	
AV _{CC}	Analog supply voltage		—	V _{CC} ³	—	V	
V _{SS}	Supply voltage		—	0	—	V	
AV _{SS}	Analog supply voltage		—	0	—	V	
V _{IH}	"H" input voltage		0.8V _{CC}	—	V _{CC}	V	
V _{IL}	"L" input voltage		0	—	0.2V _{CC}	V	
I _{OH (sum)}	"H" peak all output currents	Sum of all pins' IOH (peak)	—	—	-60.0	mA	
I _{OH (peak)}	"H" peak output current		—	—	-10.0	mA	
I _{OH (avg)}	"H" average output current		—	—	-5.0	mA	
I _{OL (sum)}	"L" peak all output currents	Sum of all pins' IOL (peak)	—	—	60	mA	
I _{OL (peak)}	"L" peak output current	Except P1 ₀ to P1 ₇	—	—	10	mA	
		P1 ₀ to P1 ₇	Drive capacity HIGH	—	—	30	mA
			Drive capacity LOW	—	—	10	mA
I _{OL (avg)}	"L" average output current	Except P1 ₀ to P1 ₇	—	—	5	mA	
		P1 ₀ to P1 ₇	Drive capacity HIGH	—	—	15	mA
			Drive capacity LOW	—	—	5	mA
f (XIN)	Main clock input oscillation frequency	3.0V ≤ V _{CC} ≤ 5.5V	0	—	20	MHz	
		2.7V ≤ V _{CC} < 3.0V	0	—	10	MHz	

Note

1: Referenced to V_{CC} = AV_{CC} = 2.7 to 5.5V at T_{opr} = -20 to 85 °C / -40 to 85 °C unless otherwise specified.

2: The mean output current is the mean value within 100ms.

3: Hold V_{CC}=AV_{CC}.

Table 5.3 A/D Conversion Characteristics

Symbol	Parameter		Measuring condition	Standard			Unit
				Min.	Typ.	Max.	
–	Resolution		$V_{ref} = V_{CC}$			10	Bit
–	Absolute accuracy	10 bit mode	$f(XIN) = \emptyset AD = 10 \text{ MHz}$, $V_{ref} = V_{CC} = 5.0V$			± 3	LSB
		8 bit mode	$f(XIN) = \emptyset AD = 10 \text{ MHz}$, $V_{ref} = V_{CC} = 5.0V$			± 2	LSB
		10 bit mode	$f(XIN) = \emptyset AD = 10 \text{ MHz}$, $V_{ref} = V_{CC} = 3.3V$			± 5	LSB
		8 bit mode	$f(XIN) = \emptyset AD = 10 \text{ MHz}$, $V_{ref} = V_{CC} = 3.3V$			± 2	LSB
R_{LADDER}	Ladder resistance		$V_{REF} = V_{CC}$	10		40	$k\Omega$
t_{CONV}	Conversion time	10 bit mode	$f(XIN) = \emptyset AD = 10 \text{ MHz}$, $V_{ref} = V_{CC} = 5.0V$	3.3			μs
		8 bit mode	$f(XIN) = \emptyset AD = 10 \text{ MHz}$, $V_{ref} = V_{CC} = 5.0V$	2.8			μs
V_{REF}	Reference voltage				V_{CC}^4		V
V_{IA}	Analog input voltage			0		V_{ref}	V
–	A/D operation clock frequency ²	Without sample & hold		0.25		10	MHz
		With sample & hold		1.0		10	MHz

Note

- 1: Referenced to $V_{CC} = AV_{CC} = 2.7$ to $5.5V$ at $T_{opr} = -20$ to $85 \text{ }^\circ C$ / -40 to $85 \text{ }^\circ C$ unless otherwise specified.
- 2: When f_{AD} is 10 MHz more, divide the f_{AD} and make A/D operation clock frequency ($\emptyset AD$) lower than 10 MHz.
- 3: When the V_{CC} is less than 4.2V, divide the f_{AD} and make A/D operation clock frequency ($\emptyset AD$) lower than $f_{AD}/2$.
- 4: Hold $V_{CC} = V_{ref}$.

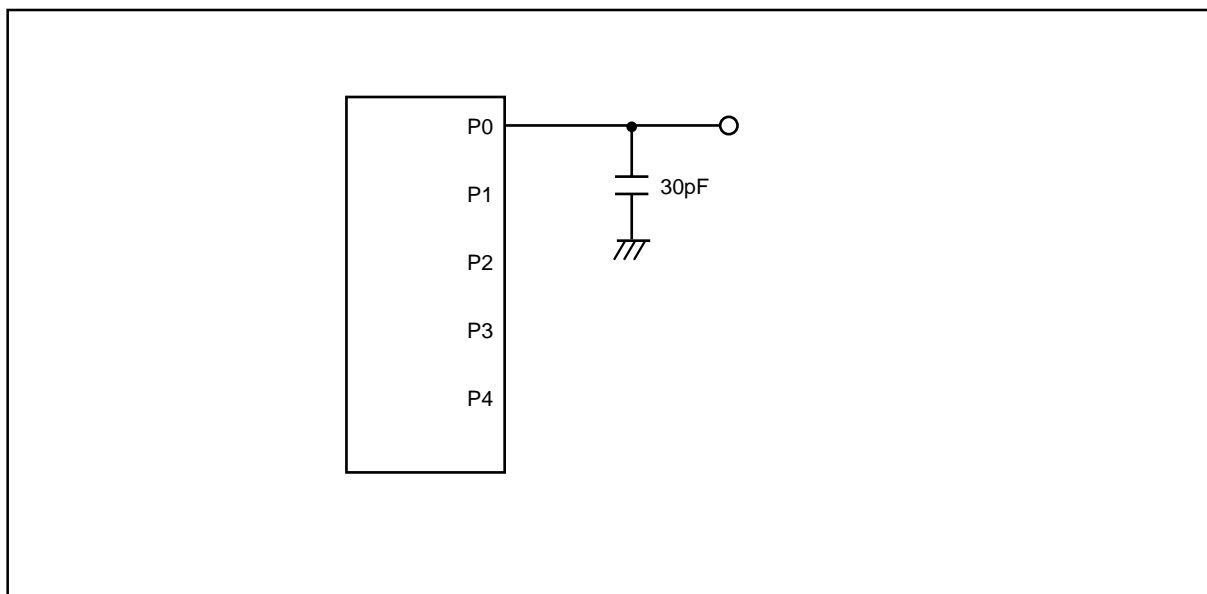


Figure 5.1 Port P0 to P4 measurement circuit

Table 5.4 Flash Memory Version Electrical Characteristics

Symbol	Parameter	Measuring condition	Standard			Unit
			Min.	Typ.	Max.	
—	Program/erase cycle		100	—	—	cycle
—	Byte program time	V _{cc} =5.0V, Topr=25 °C	—	50	400	μs
—	Block erase time	V _{cc} =5.0V, Topr=25 °C	—	0.4	9	s
td(SR-ES)	Time delay from suspend request until erase suspend		—	—	8	ms
—	Program, Erase voltage		2.7	—	5.5	V
—	Read voltage		2.7	—	5.5	V
—	Program, Erase temperature		0	—	60	°C
—	Data-retention duration	Topr=55 °C	20	—	—	year

Note

1: Referenced to V_{cc1}=AV_{cc}=2.7 to 5.5V at Topr = 0 to 60 °C unless otherwise specified.

Table 5.5 Voltage Detection Circuit Electrical Characteristics

Symbol	Parameter	Measuring condition	Min.	Standard		Unit
				Typ.	Max.	
Vdet	Voltage detection level		3.3	3.8	4.3	V
	Voltage detection interrupt request generating time ²			40		μs
	Voltage detection circuit self consumption current	V _{C27} =1, V _{CC} =5.0V		600		nA
td(E-A)	Waiting time till voltage detection circuit operation starts ³				20	μs
V _{ccmin}	Minimum value of microcomputer operation voltage		2.7			V

NOTES:

1. The measuring condition is V_{cc}=AV_{cc}=2.7V to 5.5V and Topr= -40°C to 85 °C.
2. This shows the time until the voltage detection interrupt request is generated since the voltage passes Vdet.
3. This shows the required time until the voltage detection circuit operates when setting to "1" again after setting the VC27 bit in the VCR2 register to "0"

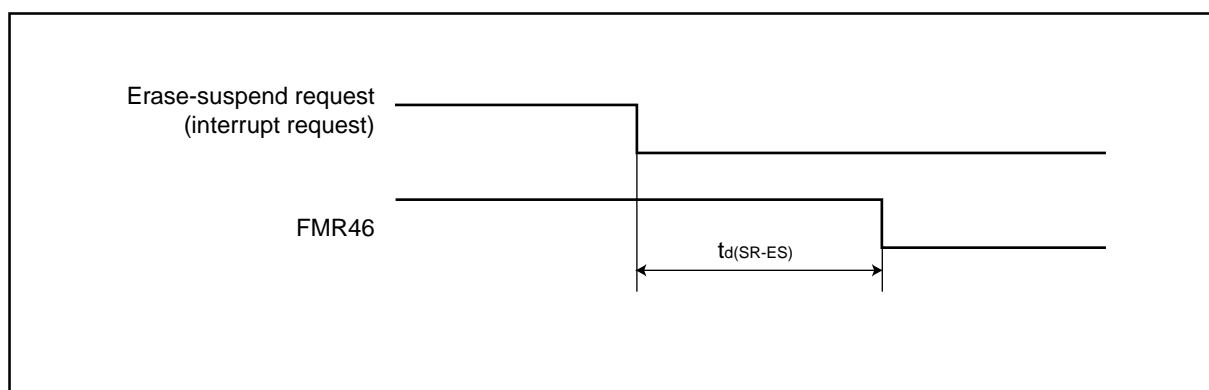
**Figure 5.2 Time delay from Suspend Request until Erase Suspend**

Table 5.6 Reset Circuit Electrical Characteristics (When Using Hardware Reset 2)

Symbol	Parameter	Measuring condition	Standard			Unit
			Min.	Typ.	Max.	
Vpor2	Power-on reset valid voltage				Vdet	V
tw(Vpor2-Vdet)	Supply voltage rising time when power-on reset is canceled ²				100	ms
tw(por2)	Time to hold external power below valid voltage		0			s

NOTES:

1. The voltage detection circuit which is embedded in a microcomputer is a factor to generate the hardware reset 2. Refer to 5.1.2 Hardware Reset 2 of Hardware Manual.
2. This condition is not applicable when using with Vcc ≥ 1.0V.
3. When turning power on after the time to hold the external power below effective voltage exceeds 10s, refer to Table 16.8 Reset Circuit Electrical Characteristics (When Not Using Voltage Monitor 1 Reset).

Table 5.7 Reset Circuit Electrical Characteristics (When Not Using Hardware Reset 2)

Symbol	Parameter	Measuring condition	Standard			Unit
			Min.	Typ.	Max.	
Vpor1	Power-on reset valid voltage				0.1	V
tw(Vpor1-Vdet)	Supply voltage rising time when power-on reset is canceled	0°C ≤ Topr ≤ 85°C			100	ms
tw(por1)	Time to hold external power on below valid voltage	0°C ≤ Topr ≤ 85°C	10			s
tw(Vpor1-Vdet)	Supply voltage rising time when power-on reset is canceled	-20°C ≤ Topr ≤ 0°C			100	ms
tw(por1)	Time to hold external power on below valid voltage	-20°C ≤ Topr ≤ 0°C	30			s
tw(Vpor1-Vdet)	Supply voltage rising time when power-on reset is canceled	-20°C ≤ Topr ≤ 0°C			1	ms
tw(por1)	Time to hold external power on below valid voltage	-20°C ≤ Topr ≤ 0°C	10			s
tw(Vpor1-Vdet)	Supply voltage rising time when power-on reset is canceled	0°C ≤ Topr ≤ 85°C			0.5	ms
tw(por1)	Time to hold external power on below valid voltage	0°C ≤ Topr ≤ 85°C	1			s

NOTES:

1. When not the sing hardware reset 2, use with Vcc ≥ 2.7V.

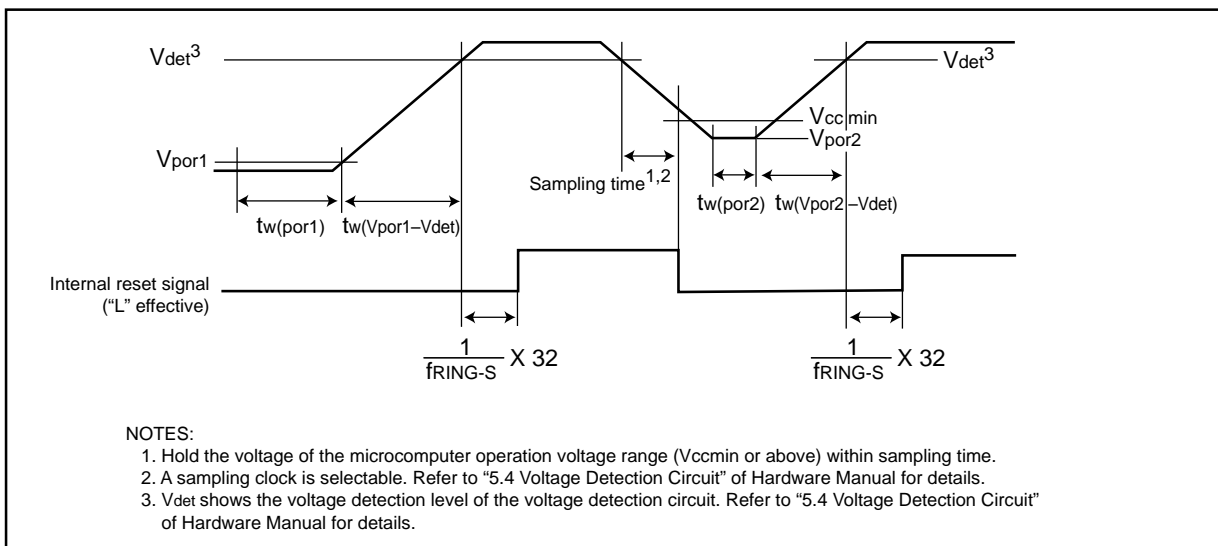


Figure 5.3 Reset Circuit Electrical Characteristics

Table 5.8 High-speed On-Chip Oscillator Circuit Electrical Characteristics

Symbol	Parameter	Measuring condition	Standard			Unit
			Min.	Typ.	Max.	
	High-speed on-chip oscillator frequency $1 / (td(HRoffset)+td(HR))$ when the reset is released	VCC=5.0V, Topr=25 °C Set "4016" in the HR1 register	6	8	10	MHz
td(HRoffset)	Settable high-speed on-chip oscillator minimum period	VCC=5.0V, Topr=25 °C Set "0016" in the HR1 register		61		ns
td(HR)	High-speed on-chip oscillator period adjusted unit	Differences when setting "0116" and "0016" in the HR register		1		ns
	High-speed on-chip oscillator temperature dependence(1)	Frequency fluctuation in temperature range of -10 °C to 50 °C		±5		%
	High-speed on-chip oscillator temperature dependence(2)	Frequency fluctuation in temperature range of -40 °C to 85 °C		±10		%

NOTES:

1. The measuring condition is Vcc=AVcc=5.0 V and Topr=25 °C.

Table 5.9 Power Circuit Timing Characteristics

Symbol	Parameter	Measuring condition	Standard			Unit
			Min.	Typ.	Max.	
td(P-R)	Time for internal power supply stabilization during powering-on ²				2	ms
td(R-S)	STOP release time ³				150	µs

Note

1: The measuring condition is Vcc=AVcc=2.7 to 5.5 V and Topr=25 °C.

2: This shows the wait time until the internal power supply generating circuit is stabilized during power-on.

3: This shows the time until BCLK starts from the interrupt acknowledgement to cancel stop mode.

Table 5.10 Electrical Characteristics (1) [Vcc=5V]

Symbol	Parameter		Measuring condition	Standard			Unit
				Min.	Typ.	Max.	
VoH	"H" output voltage	Except XOUT	IOH=-5mA	Vcc-2.0		Vcc	V
			IOH=-200µA	Vcc-0.3		Vcc	V
		XOUT	Drive ability HIGH IOH=-1 mA	Vcc-2.0		Vcc	V
			Drive ability LOW IOH=-500µA	Vcc-2.0		Vcc	V
VoL	"L" output voltage	P10 to P17 Except XOUT	IOH= 5 mA			2.0	V
			IOH= 200 µA			0.45	V
		P10 to P17	Drive capacity HIGH IOL= 15 mA			2.0	V
			Drive capacity LOW IOL= 5 mA			2.0	V
			Drive capacity LOW IOL= 200 µA			0.45	V
		XOUT	Drive capacity HIGH IOL= 1 mA			2.0	V
			Drive capacity LOW IOL=500 µA			2.0	V
		VT+-VT-	Hysteresis	INT0, INT1, INT2, INT3, K10, K11, K12, K13, CNTR0, CNTR1, TCIN, RxD0, RxD1		0.2	
RESET				0.2		2.2	V
IiH	"H" input current		Vi=5V			5.0	µA
IiL	"L" input current		Vi=0V			-5.0	µA
RPULLUP	Pull-up resistance		Vi=0V	30	50	167	kΩ
RiXIN	Feedback resistance	XIN			1.0		MΩ
fRING-S	Low-speed on-chip oscillator frequency			40	125	250	kHz
VRAM	RAM retention voltage		At stop mode	2.0			V

Note

1 : Referenced to Vcc=AVcc=4.2 to 5.5V at Topr = -20 to 85 °C / -40 to 85 °C, f(BCLK)=20MHz unless otherwise specified.

Table 5.11 Electrical Characteristics (2) [Vcc=5V]

Symbol	Parameter	Measuring condition		Standard			Unit
				Min.	Typ.	Max.	
Icc	Power supply current (Vcc=3.3 to 5.5V) In single-chip mode, the output pins are open and other pins are Vss	High-speed mode	XIN=20 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on=125 kHz No division		9	15	mA
			XIN=16 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on=125 kHz No division		8	14	mA
			XIN=10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on=125 kHz No division		5		mA
		Medium-speed mode	XIN=20 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on=125 kHz Division by 8		4		mA
			XIN=16 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on=125 kHz Division by 8		3		mA
			XIN=10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on=125 kHz Division by 8		2		mA
		High-speed on-chip oscillator mode	Main clock off High-speed on-chip oscillator on=8 MHz Low-speed on-chip oscillator on=125 kHz No division		4	8	mA
			Main clock off High-speed on-chip oscillator on=8 MHz Low-speed on-chip oscillator on=125 kHz Division by 8		1.5		mA
		Low-speed on-chip oscillator mode	Main clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on=125 kHz Division by 8		470	900	μA
		Wait mode	Main clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on=125 kHz When a WAIT instruction is executed ¹ Peripheral clock operation VC27="0"		40	80	μA
Wait mode	Main clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on=125 kHz When a WAIT instruction is executed ² Peripheral clock off VC27="0"		38	76	μA		
Stop mode	Main clock off High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10="1" Peripheral clock off VC27="0"		0.8	3.0	μA		

NOTES

- 1: The power supply current measuring is executed using the measuring program on flash memory.
- 2: Timer Y is operated with timer mode.

Timing requirements (Unless otherwise noted: $V_{CC} = 5V$, $V_{SS} = 0V$ at $T_a = 25\text{ }^\circ\text{C}$) [$V_{CC}=5V$]**Table 5.12 XIN input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
tC(XIN)	XIN input cycle time	50		ns
tWH(XIN)	XIN input HIGH pulse width	25		ns
tWL(XIN)	XIN input LOW pulse width	25		ns

Table 5.13 CNTR0 input, CNTR1 input, $\overline{\text{INT2}}$ input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
tC(CNTR0)	CNTR0 input cycle time	100		ns
tWH(CNTR0)	CNTR0 input HIGH pulse width	40		ns
tWL(CNTR0)	CNTR0 input LOW pulse width	40		ns

Table 5.14 TCIN input, $\overline{\text{INT3}}$ input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
tC(TCIN)	TCIN input cycle time	400 ⁽¹⁾		ns
tWH(TCIN)	TCIN input HIGH pulse width	200 ⁽²⁾		ns
tWL(TCIN)	TCIN input LOW pulse width	200 ⁽²⁾		ns

NOTES

- 1 :When using the Timer C input capture mode, adjust the cycle time above (1/ Timer C count source frequency x 3).
- 2 : When using the Timer C input capture mode, adjust the pulse width above (1/ Timer C count source frequency x 1.5).

Table 5.15 Serial Interface

Symbol	Parameter	Standard		Unit
		Min.	Max.	
tC(CK)	CLKi input cycle time	200		ns
tW(CKH)	CLKi input HIGH pulse width	100		ns
tW(CKL)	CLKi input LOW pulse width	100		ns
td(C-Q)	TxDi output delay time		80	ns
th(C-Q)	TxDi hold time	0		ns
tsu(D-C)	RxDi input setup time	35		ns
th(C-D)	RxDi input hold time	90		ns

Table 5.16 External interrupt $\overline{\text{INT0}}$ input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
tW(INH)	$\overline{\text{INT0}}$ input HIGH pulse width	250 ⁽¹⁾		ns
tW(INL)	$\overline{\text{INT0}}$ input LOW pulse width	250 ⁽²⁾		ns

NOTES

- 1 : When selecting the digital filter by the $\overline{\text{INT0}}$ input filter select bit, use the $\overline{\text{INT0}}$ input HIGH pulse width to the greater value, either (1/ digital filter clock frequency x 3) or the minimum value of standard.
- 2 : When selecting the digital filter by the $\overline{\text{INT0}}$ input filter select bit, use the $\overline{\text{INT0}}$ input LOW pulse width to the greater value, either (1/ digital filter clock frequency x 3) or the minimum value of standard.

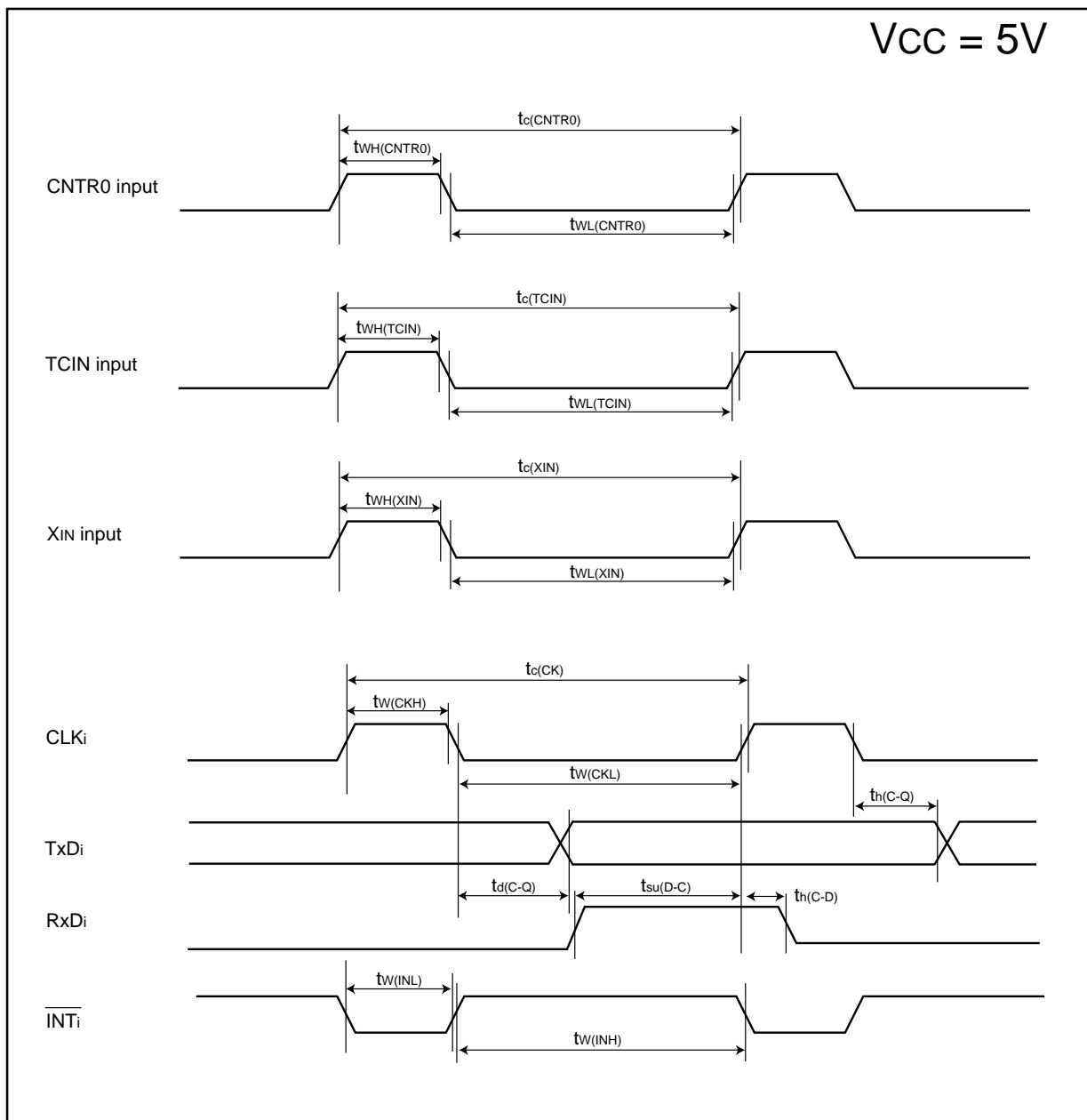


Figure 5.4 Vcc=5V timing diagram

Table 5.17 Electrical Characteristics (3) [V_{CC}=3V]

Symbol	Parameter		Measuring condition	Standard			Unit
				Min.	Typ.	Max.	
V _{OH}	"H" output voltage	Except X _{OUT}	I _{OH} =-1mA	V _{CC} -0.5		V _{CC}	V
		X _{OUT}	Drive capacity HIGH I _{OH} =-0.1 mA	V _{CC} -0.5		V _{CC}	V
			Drive capacity LOW I _{OH} =-50 μA	V _{CC} -0.5		V _{CC}	V
V _{OL}	"L" output voltage	P10 to P17 Except X _{OUT}	I _{OH} = 1 mA			0.5	V
		P10 to P17	Drive capacity HIGH I _{OL} = 2 mA			0.5	V
			Drive capacity LOW I _{OL} = 1 mA			0.5	V
		X _{OUT}	Drive capacity HIGH I _{OL} = 0.1 mA			0.5	V
			Drive capacity LOW I _{OL} =50 μA			0.5	V
V _{T+} -V _{T-}	Hysteresis	INT0, INT1, INT2, INT3, K10, K11, K12, K13, CNTR0, CNTR1, TCIN, RxD0, RxD1		0.2		0.8	V
		RESET		0.2		1.8	V
I _{IH}	"H" input current		V _I =3V			4.0	μA
I _{IL}	"L" input current		V _I =0V			-4.0	μA
R _{PULLUP}	Pull-up resistance		V _I =0V	66	160	500	kΩ
R _{XIN}	Feedback resistance	X _{IN}			3.0		MΩ
f _{RING-S}	Low-speed on-chip oscillator frequency			40	125	250	kHz
V _{RAM}	RAM retention voltage		At stop mode	2.0			V

Note

1 : Referenced to V_{CC}=AV_{CC}=2.7 to 3.3V at T_{opr} = -20 to 85 °C / -40 to 85 °C, f(BCLK)=10MHz unless otherwise specified.

Table 5.18 Electrical Characteristics (4) [V_{CC}=3V]

Symbol	Parameter	Measuring condition		Standard			Unit
				Min.	Typ.	Max.	
I _{CC}	Power supply current (V _{CC} =2.7 to 3.3V) In single-chip mode, the output pins are open and other pins are V _{SS}	High-speed mode	XIN=20 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on=125 kHz No division		8	13	mA
			XIN=16 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on=125 kHz No division		7	12	mA
			XIN=10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on=125 kHz No division		5		mA
		Medium-speed mode	XIN=20 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on=125 kHz Division by 8		3		mA
			XIN=16 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on=125 kHz Division by 8		2.5		mA
			XIN=10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on=125 kHz Division by 8		1.6		mA
		High-speed on-chip oscillator mode	Main clock off High-speed on-chip oscillator on=8 MHz Low-speed on-chip oscillator on=125 kHz No division		3.5	7.5	mA
			Main clock off High-speed on-chip oscillator on=8 MHz Low-speed on-chip oscillator on=125 kHz Division by 8		1.5		mA
		Low-speed on-chip oscillator mode	Main clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on=125 kHz Division by 8		420	800	μA
		Wait mode	Main clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on=125 kHz When a WAIT instruction is executed ² Peripheral clock operation VC27="0"		37	74	μA
		Wait mode	Main clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on=125 kHz When a WAIT instruction is executed ² Peripheral clock off VC27="0"		35	70	μA
		Stop mode	Main clock off High-speed on-chip oscillator off Low-speed on-chip oscillator off OM10="1" Peripheral clock off VC27="0"		0.7	3.0	μA

Note

- 1: The power supply current measuring is executed using the measuring program on flash memory.
- 2: Timer Y is operated with timer mode.

Timing requirements (Unless otherwise noted: $V_{CC} = 3V$, $V_{SS} = 0V$ at $T_a = 25\text{ }^\circ\text{C}$) [$V_{CC}=3V$]**Table 5.19 XIN input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
t _C (XIN)	XIN input cycle time	100		ns
t _{WH} (XIN)	XIN input HIGH pulse width	40		ns
t _{WL} (XIN)	XIN input LOW pulse width	40		ns

Table 5.20 CNTR0 input, CNTR1 input, $\overline{\text{INT2}}$ input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
t _C (CNTR0)	CNTR0 input cycle time	300		ns
t _{WH} (CNTR0)	CNTR0 input HIGH pulse width	120		ns
t _{WL} (CNTR0)	CNTR0 input LOW pulse width	120		ns

Table 5.21 TCIN input, $\overline{\text{INT3}}$ input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
t _C (TCIN)	TCIN input cycle time	1200 ⁽¹⁾		ns
t _{WH} (TCIN)	TCIN input HIGH pulse width	600 ⁽²⁾		ns
t _{WL} (TCIN)	TCIN input LOW pulse width	600 ⁽²⁾		ns

NOTES

- 1 : When using the Timer C input capture mode, adjust the cycle time above (1/ Timer C count source frequency x 3).
- 2 : When using the Timer C input capture mode, adjust the pulse width above (1/ Timer C count source frequency x 1.5).

Table 5.22 Serial Interface

Symbol	Parameter	Standard		Unit
		Min.	Max.	
t _C (CK)	CLKi input cycle time	300		ns
t _W (CKH)	CLKi input HIGH pulse width	150		ns
t _W (CKL)	CLKi input LOW pulse width	150		ns
t _d (C-Q)	TxDi output delay time		160	ns
t _h (C-Q)	TxDi hold time	0		ns
t _{su} (D-C)	RxDi input setup time	55		ns
t _h (C-D)	RxDi input hold time	90		ns

Table 5.23 External interrupt $\overline{\text{INT0}}$ input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
t _W (INH)	$\overline{\text{INT0}}$ input HIGH pulse width	380 ⁽¹⁾		ns
t _W (INL)	$\overline{\text{INT0}}$ input LOW pulse width	380 ⁽²⁾		ns

NOTES

- 1 : When selecting the digital filter by the $\overline{\text{INT0}}$ input filter select bit, use the $\overline{\text{INT0}}$ input HIGH pulse width to the greater value, either (1/ digital filter clock frequency x 3) or the minimum value of standard.
- 2 : When selecting the digital filter by the $\overline{\text{INT0}}$ input filter select bit, use the $\overline{\text{INT0}}$ input LOW pulse width to the greater value, either (1/ digital filter clock frequency x 3) or the minimum value of standard.

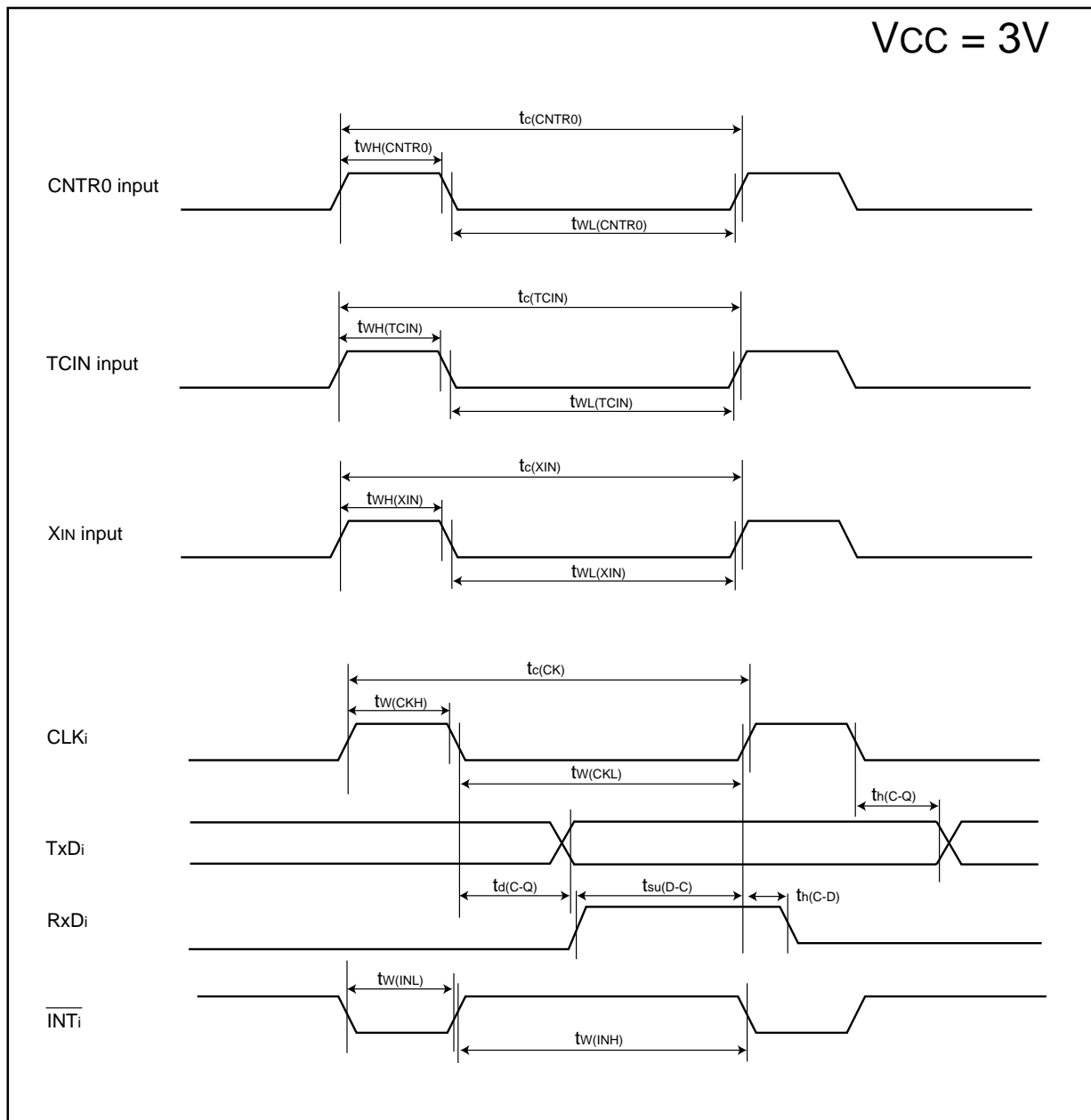


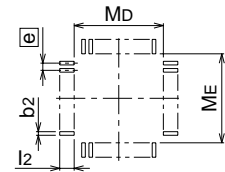
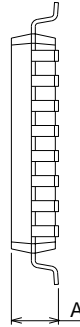
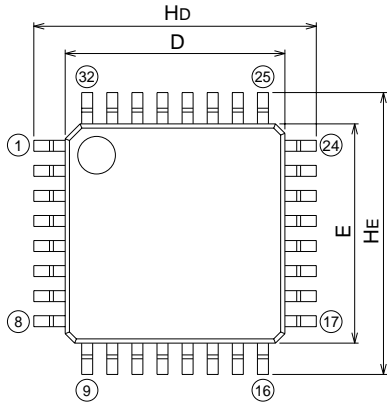
Figure 5.5 Vcc=3V timing diagram

Package Dimensions

32P6U-A

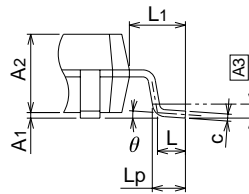
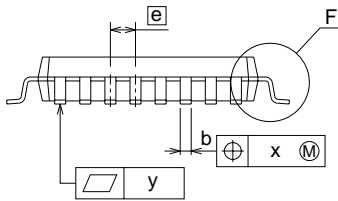
Plastic 32pin 7X7mm body LQFP

EIAJ Package Code	JEDEC Code	Weight(g)	Lead Material
LQFP32-P-0707-0.80	—		Cu Alloy



Recommended Mount Pad

Symbol	Dimension in Millimeters		
	Min	Nom	Max
A	—	—	1.7
A1	0	0.1	0.2
A2	—	1.4	—
b	0.32	0.37	0.45
c	0.105	0.125	0.175
D	6.9	7.0	7.1
E	6.9	7.0	7.1
e	—	0.8	—
H _d	8.8	9.0	9.2
H _E	8.8	9.0	9.2
L	0.3	0.5	0.7
L1	—	1.0	—
L _p	0.45	0.6	0.75
A3	—	0.25	—
x	—	—	0.2
y	—	—	0.1
θ	0 _i	—	10 _i
b ₂	—	0.5	—
l ₂	1.0	—	—
M _d	—	7.4	—
M _E	—	7.4	—



Detail F

REVISION HISTORY

R8C/11 Group Datasheet

Rev.	Date	Description	
		Page	Summary
1.00	Jun. 19, 2003		First edition issued
1.10	Sep. 08, 2003	2 5 6 10 12 14	Table 1.1: Shortest instruction execution time and $f(X_{IN})$ changed Figure 1.3: Pin name changed from TXOUT to $\overline{CNTR0}$ Table 1.3: Pin name changed from TXOUT to $\overline{CNTR0}$ The value of HR1 register after reset changed The value of TC register after reset changed Chapter "5. Electrical Characteristics" added
1.20	Oct. 31, 2003	2 6 11 14 15 17 19 20 21 22 23 24 25	Table 1.1: Power consumption values added Table 1.3: Resistor value for CNV_{SS} and MODE deleted Register name of address 0050 ₁₆ modified from CMP2IC to CMP1IC, register name of address 005C ₁₆ modified from CMP1IC to CMP0IC Table 5.2: Note 3 and Note 4 deleted t_{SAMP} in Table 5.3 deleted Figure 5.1 added Table 5.10: V_{CC} changed from "4.2 to 5.5V" to "3.3V to 5.5V", low-power ring oscillator changed from "on 100kHz" to "125kHz", $X_{IN}=5MHz$ deleted and $X_{IN}=10MHz$ added in high-speed mode and medium-speed mode, $VC27="0"$ added in stop mode measuring condition, data added and modified Table 11 to Table 15 added Figure 5.2 added Table 5.16: Note 1, $f_{(BCLK)}=5 MHz$ changed to 10 MHz Table 5.17: low-power ring oscillator changed from "on 100kHz" to "125kHz", $X_{IN}=5MHz$ deleted and $X_{IN}=10MHz$ added in high-speed mode and medium-speed mode, $VC27="0"$ added in stop mode measuring condition, data added and modified Table 5.18 to Table 5.22 added Figure 5.3 added
1.30	Dec 05, 2003	4 15	Table 1.2 : ** deleted Table 5.4 revised
1.40	Sep 30, 2004	all pages 2 5 6 9 10-13 12 14 15 16 17 18	Words standardized (on-chip oscillator, serial interface, A/D) Table 1.1 revised Figure 1.3, NOTES 3 added Table 1.3 revised Figure 3.1, NOTES added One body sentence in chapter 4 added ; Title of Table 4.1 to 4.4 added Table 4.3 revised ; Table 4.4 revised Table 5.2 revised Table 5.3 revised Table 5.4 revised ; Table 16.5 revised Table 5.6, 5.7 adn 5.8 revised ; Figure 5.3 revised Table 5.9 revised ; Table 5.10 revised

REVISION HISTORY

R8C/11 Group Datasheet

Rev.	Date	Description	
		Page	Summary
1.40	Sep 30, 2004	20	Table 5.12 revised ; Table 5.16 revised
		22	Table 16.17 revised
		24	Table 16.19 revised

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